



Initial Product/Process Change Notification

Document #: IPCN26978XA

Issue Date: 31 Mar 2026

Title of Change:	Wafer Fab and Test Site Change for ST3 Products from Mountain Top, USA to Bucheon, Korea.	
Proposed First Ship date:	01 Oct 2026 or earlier if approved by customer	
Current Material Last Order Date:	31 May 2026 <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i>	
Contact Information:	Contact your local onsemi Sales Office	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <	
Marking of Parts/ Traceability of Change:	The changed material can be identified by lot code and date code.	
Change Category:	Wafer Fab Change, Test Change	
Change Sub-Category(s):	Manufacturing Site Transfer	
Sites Affected:		
onsemi Sites	External Foundry/Subcon Sites	
onsemi Bucheon, Korea	None	
Description and Purpose:		
This is an Initial Change Notification to inform customers of the qualification of onsemi Bucheon, Korea facility as NEW wafer fab site for ST3 Technology. FPCNs to be issued in July of 2026 with first ship date as referenced above from Bucheon fab. If your FPCN approval will extend beyond the proposed first ship date, provide unit requirements for the unchanged material to your onsemi sales representative no later than May 31, 2026 by NCNR PO (Last order date for unchanged material). These bridge quantities will be limited and will be considered on a first-come, first-serve basis. onsemi will work with customers to facilitate the approval of the FPCNs by providing early samples and matching electrical data upon request, prior to the final PCN notices in July of 2026 to reduce customers' need for additional unchanged material. Early samples are processed according to final process and condition as released in the FPCN. No changes will occur between early samples and after FPCN issuance.		
	Before Change Description	After Change Description
FAB Site	Mountain Top, PA, USA	onsemi Bucheon, Korea
Backgrind Site	Mountain Top, PA, USA	onsemi Bucheon, Korea
Probe Site	Mountain Top, PA, USA and Bucheon, Korea	onsemi Bucheon, Korea



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Qualification Plan:

QV DEVICE NAME : FDS6681Z

RMS : 98262

PACKAGE : SOIC-8

Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Tj = Max rate Tj for device, bias =100% of rated V (Not to exceed max rated)	1,008 hrs
High Temperature Gate Bias	JESD22-A108	Tj = Max rate Tj for device, Max Vgs	1,008 hrs
High Temperature Storage Life	JESD22-A103	Ta =Max rate storage temp for device	1,008 hrs
Precondition (PC)	J-STD-020, JESD22-A113	IR reflow at 245C or 260C (pkg dependant)	-
(PC+) Highly Accelerated Stress Test	JESD22-A110	Temp = 130C, 85% RH, ~ 18.8 psig, bias = 80% of rated V or 100V max	96 hrs
(PC+) Unbiased Highly Accelerated Stress Test	JESD22-A118	Temp = 130C, RH=85%, ~ 18.8 psig	96 hrs
(PC+) Temp Cycling	JESD22-A104	Temp = -55°C to +150°C	1,000 cyc
(PC+) Intermittent Operating Life	MIL STD750, M 1037, AEC Q101	Ta=+25°C, deltaTj=100°C max, 2 min Ton=Toff	15,000 cyc

Estimated date for qualification completion: **1 July 2026**

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Current Part Number	New Part Number	Qualification Vehicle
FDC642P	#NONE	FDS6681Z
FDC608PZ	#NONE	FDS6681Z
FDC610PZ	#NONE	FDS6681Z
FDMC510P	#NONE	FDS6681Z
FDS6681Z	#NONE	FDS6681Z
FDC638APZ	#NONE	FDS6681Z
FDMA507PZ	#NONE	FDS6681Z
FDMA530PZ	#NONE	FDS6681Z
FDS4435BZ	#NONE	FDS6681Z
FDS4935BZ	#NONE	FDS6681Z
FDS6673BZ	#NONE	FDS6681Z
FDS6675BZ	#NONE	FDS6681Z
FDS6679AZ	#NONE	FDS6681Z
FDS8858CZ	#NONE	FDS6681Z
FDC610PZ-G	#NONE	FDS6681Z



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FDMA1023PZ	#NONE	FDS6681Z
FDMA1029PZ	#NONE	FDS6681Z
FDMA1032CZ	#NONE	FDS6681Z
FDMA3023PZ	#NONE	FDS6681Z
FDMC4435BZ	#NONE	FDS6681Z
FDMC6675BZ	#NONE	FDS6681Z
FDMC6679AZ	#NONE	FDS6681Z
FDMS4435BZ	#NONE	FDS6681Z
FDY1002PZ	#NONE	FDS6681Z
FDY102PZ	#NONE	FDS6681Z
FDMS6673BZ-NC	#NONE	FDS6681Z
FDMS4435BZ-NC	#NONE	FDS6681Z
FDC638APZ-PSBMS001	#NONE	FDS6681Z
FDC638APZ-SBMS001	#NONE	FDS6681Z
FDMC4435BZ-F127	#NONE	FDS6681Z
FDMC6675BZ-P	#NONE	FDS6681Z
FDMS6681Z-P	#NONE	FDS6681Z
FDME1034CZT	#NONE	FDS6681Z
FDMS6673BZ	#NONE	FDS6681Z



Initial Product/Process Change Notification

Document #: IPCN26978XA2

Issue Date: 29 Jul 2026

Title of Change:	Update to IPCN26978XA - Wafer Fab and Test Site Change for ST3 Products from Mountain Top, USA to Bucheon, Korea.	
Proposed First Ship date:	21 Jun 2027 or earlier if approved by customer	
Contact Information:	Contact your local onsemi Sales Office	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact	
Marking of Parts/ Traceability of Change:	The changed material can be identified by lot code and date code.	
Change Category:	Test Change, Wafer Fab Change	
Change Sub-Category(s):	Manufacturing Site Transfer	
Sites Affected:		
onsemi Sites	External Foundry/Subcon Sites	
onsemi Bucheon, Korea	None	
Description and Purpose:		
This Update Notification is to inform customers of the qualification of onsemi Bucheon, Korea facility as NEW wafer fab site for ST3 Technology. FPCNs to be issued in October of 2026 with first ship date as referenced above from Bucheon fab. If your FPCN approval will extend beyond the proposed first ship date, provide unit requirements for the unchanged material to your onsemi sales representative no later than May 31, 2026, by NCNR PO (Last order date for unchanged material). These bridge quantities will be limited and will be considered on a first-come, first-serve basis. onsemi will work with customers to facilitate the approval of the FPCNs by providing early samples and matching electrical data upon request, prior to the final PCN notices in October of 2026 to reduce customers' need for additional unchanged material. Early samples are processed according to final process and condition as released in the FPCN. No changes will occur between early samples and after FPCN issuance.		
	Before Change Description	After Change Description
FAB Site	Mountain Top, PA, USA	onsemi Bucheon, Korea
Backgrind Site	Mountain Top, PA, USA	onsemi Bucheon, Korea
Probe Site	Mountain Top, PA, USA and onsemi Bucheon, Korea	onsemi Bucheon, Korea
OPN naming	No change	-BK suffix added
There is no product marking change as a result of this change.		



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Qualification Plan:

QV DEVICE NAME : FDS6681Z

RMS : 98262

PACKAGE : SOIC-8

Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Tj = Max rate Tj for device, bias =100% of rated V (Not to exceed max rated)	1,008 hrs
High Temperature Gate Bias	JESD22-A108	Tj = Max rate Tj for device, Max Vgs	1,008 hrs
High Temperature Storage Life	JESD22-A103	Ta =Max rate storage temp for device	1,008 hrs
Precondition (PC)	J-STD-020, JESD22-A113	IR reflow at 245C or 260C (pkg dependant)	-
(PC+) Highly Accelerated Stress Test	JESD22-A110	Temp = 130C, 85% RH, ~ 18.8 psig, bias = 80% of rated V or 100V max	96 hrs
(PC+) Unbiased Highly Accelerated Stress Test	JESD22-A118	Temp = 130C, RH=85%, ~ 18.8 psig	96 hrs
(PC+) Temp Cycling	JESD22-A104	Temp = -55°C to +150°C	1,000 cyc
(PC+) Intermittent Operating Life	MIL STD750, M 1037, AEC Q101	Ta=+25°C, deltaTj=100°C max, 2 min Ton=Toff	15,000 cyc

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Current Part Number	New Part Number	Qualification Vehicle
FDME1034CZT	FDME1034CZT-BK	FDS6681Z
FDMA1032CZ	FDMA1032CZ-BK	FDS6681Z
FDS8858CZ	FDS8858CZ-BK	FDS6681Z